

1. General Description

The 74HC125; 74HCT125 is a quad buffer/line driver with 3-state outputs controlled by the output enable inputs (\overline{nOE}). A HIGH on \overline{nOE} causes the outputs to assume a high impedance OFF-state. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

2. Features and Benefits

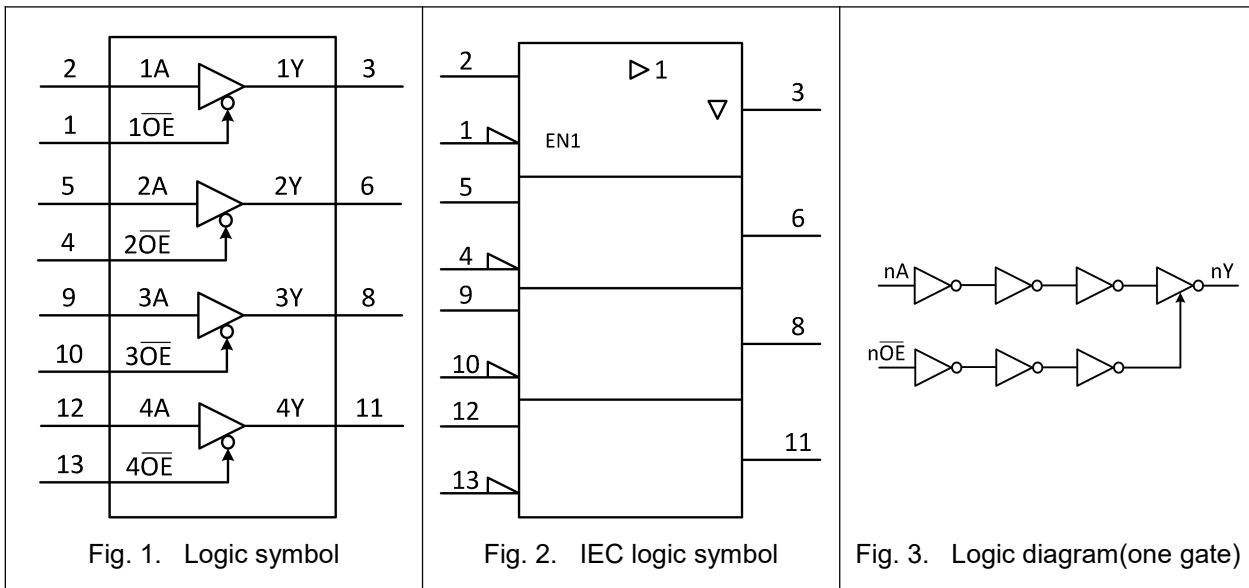
- Wide supply voltage range from 2.0 V to 6.0 V
- High noise immunity
- CMOS low power dissipation
- Latch-up performance exceeds 250 mA
- Complies with JEDEC standards:
 - JESD8C (2.7 V to 3.6 V)
 - JESD7A (2.0 V to 6.0 V)
- Input levels:
 - For 74HC125: CMOS level
 - For 74HCT125: TTL level
- ESD protection:
 - HBM ANSI/ESDA/JEDEC JS-001 Class 2 exceeds 3500 V
 - CDM ANSI/ESDA/JEDEC JS-002 Class C3 exceeds 2000 V
- Multiple package options

3. Ordering Information

Table 1. Ordering information

Type number	Package		
	Name	Description	Quantity
74HC125D	SOP-14L	plastic small outline package; 14 leads; body width 3.9 mm	2500
74HCT125D			
74HC125PW	TSSOP-14L	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	2500
74HCT125PW			

4. Function Diagram



5. Pinning Information

5.1. Pinning

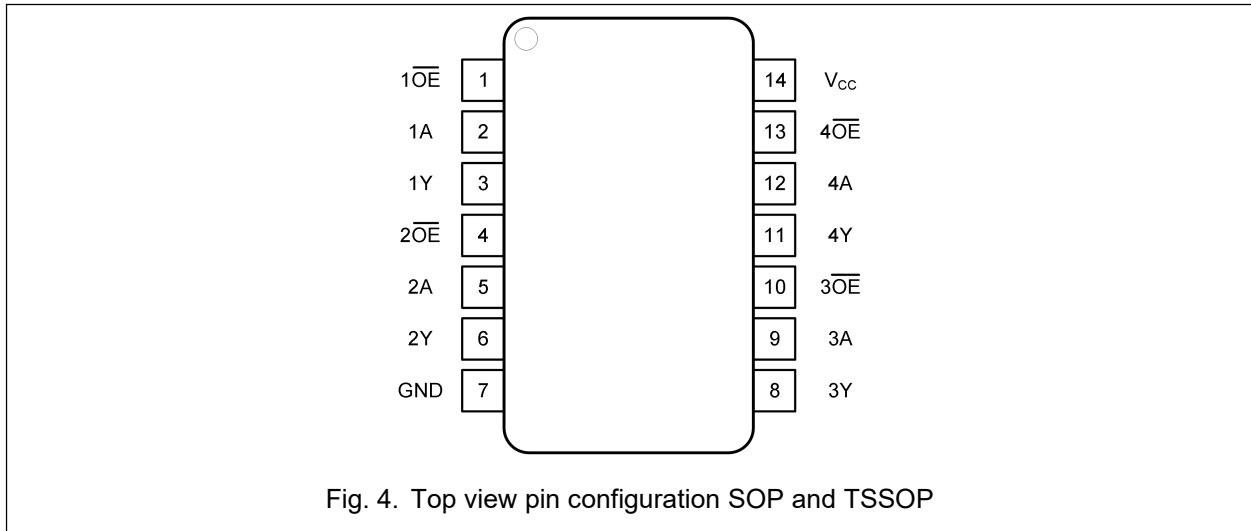


Fig. 4. Top view pin configuration SOP and TSSOP

5.2. Pin description

Table 2. Pin description

Symbol	Pin	Description
$1\overline{OE}$, $2\overline{OE}$, $3\overline{OE}$, $4\overline{OE}$	1, 4, 10, 13	Data enable input(active LOW)
1A, 2A, 3A, 4A	2, 5, 9, 12	Data input
1Y, 2Y, 3Y, 4Y	3, 6, 8, 11	Data output
GND	7	Ground (0V)
V _{CC}	14	Supply voltage

6. Functional Description

Table 3. Function table

H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

Input		Output
$n\overline{OE}$	nA	nY
L	L	L
L	H	H
H	X	Z

7. Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Table 4. Absolute Maximum Ratings

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND.

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	7.0	V
I _{IK}	input clamping current	V _I < -0.5 V or V _I > V _{CC} + 0.5 V [1]		±20	mA
I _{OK}	output clamping current	V _O < -0.5 V or V _O > V _{CC} + 0.5 V [1]		±20	mA
I _O	output current	V _O = -0.5 V to (V _{CC} + 0.5 V)		±35	mA
I _{CC}	supply current			70	mA
I _{GND}	ground current		-70		mA
P _{tot}	total power dissipation			500	mW
T _{stg}	storage temperature		-65	150	°C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

8. Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. EnergyMath does not recommend exceeding them or designing to Absolute Maximum Ratings.

Table 5. Recommended Operating Conditions

Symbol	Parameter	Conditions	74HC125			74HCT125			Unit
			Min	Typ	Max	Min	Typ	Max	
V _{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V _I	input voltage		0		V _{CC}	0		V _{CC}	V
V _O	output voltage		0		V _{CC}	0		V _{CC}	V
T _{amb}	ambient temperature		-40		125	-40		125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 2.0 V			625				ns/V
		V _{CC} = 4.5 V		1.67	139		1.67	139	ns/V
		V _{CC} = 6.0 V			83				ns/V

9. Static Characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V). Typical values measured at $T_{amb} = 25^{\circ}\text{C}$ (unless otherwise noted).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	
74HC125								
V_{IH}	HIGH-level input voltage	$V_{CC} = 2.0\text{ V}$	1.5			1.5		V
		$V_{CC} = 4.5\text{ V}$	3.15			3.15		V
		$V_{CC} = 6.0\text{ V}$	4.2			4.2		V
V_{IL}	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$			0.5		0.5	V
		$V_{CC} = 4.5\text{ V}$			1.35		1.35	V
		$V_{CC} = 6.0\text{ V}$			1.8		1.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}						
		$I_O = -20\text{ }\mu\text{A}$; $V_{CC} = 2.0\text{ V}$	1.9			1.9		V
		$I_O = -20\text{ }\mu\text{A}$; $V_{CC} = 4.5\text{ V}$	4.4			4.4		V
		$I_O = -20\text{ }\mu\text{A}$; $V_{CC} = 6.0\text{ V}$	5.9			5.9		V
		$I_O = -6.0\text{ mA}$; $V_{CC} = 4.5\text{ V}$	3.84			3.7		V
		$I_O = -7.8\text{ mA}$; $V_{CC} = 6.0\text{ V}$	5.34			5.2		V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}						
		$I_O = 20\text{ }\mu\text{A}$; $V_{CC} = 2.0\text{ V}$			0.1		0.1	V
		$I_O = 20\text{ }\mu\text{A}$; $V_{CC} = 4.5\text{ V}$			0.1		0.1	V
		$I_O = 20\text{ }\mu\text{A}$; $V_{CC} = 6.0\text{ V}$			0.1		0.1	V
		$I_O = 6.0\text{ mA}$; $V_{CC} = 4.5\text{ V}$			0.33		0.4	V
		$I_O = 7.8\text{ mA}$; $V_{CC} = 6.0\text{ V}$			0.33		0.4	V
I_I	input leakage current	$V_I = V_{CC}$ or GND ; $V_{CC} = 6.0\text{ V}$			± 1		± 1	μA
I_{OZ}	OFF-state output current	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 6.0\text{ V}$; $V_O = V_{CC}$ or GND			± 5		± 10	μA
I_{CC}	supply current	$V_I = V_{CC}$ or GND ; $I_O = 0\text{ A}$; $V_{CC} = 6.0\text{ V}$			20		40	μA
C_I	input capacitance			7				pF

74HC125; 74HCT125

Quad buffer/line driver; 3-state

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	
74HCT125								
V_{IH}	HIGH-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2.0			2.0		V
V_{IL}	LOW-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$			0.8		0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}; V_{CC} = 4.5 \text{ V}$						
		$I_O = -20 \mu\text{A};$	4.4			4.4		V
		$I_O = -6.0 \text{ mA};$	3.84			3.7		V
V_{OL}	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}; V_{CC} = 4.5 \text{ V}$						
		$I_O = 20 \mu\text{A};$			0.1		0.1	V
		$I_O = 6.0 \text{ mA};$			0.33		0.4	V
I_I	input leakage current	$V_I = V_{CC} \text{ or } \text{GND}; V_{CC} = 5.5 \text{ V}$			± 1		± 1	μA
I_{OZ}	OFF-state output current	$V_I = V_{IH} \text{ or } V_{IL}; V_{CC} = 5.5 \text{ V}; V_O = V_{CC} \text{ or } \text{GND}$			± 5		± 10	μA
I_{CC}	supply current	$V_I = V_{CC} \text{ or } \text{GND}; I_O = 0 \text{ A}; V_{CC} = 5.5 \text{ V}$			20		40	μA
ΔI_{CC}	additional supply current	per pin ; $V_I = V_{CC} - 2.1 \text{ V}; I_O = 0 \text{ A};$ other inputs at V_{CC} or $\text{GND}; V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$			1.55		1.85	mA
C_I	input capacitance			10				pF

10. Dynamic Characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 7. Typical values measured at $T_{amb} = 25^{\circ}\text{C}$ (unless otherwise noted).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	
74HC125								
t_{pd}	propagation delay	nA to nY; see Fig. 5 [1]						
		$V_{CC} = 2.0\text{ V}$			35		40	ns
		$V_{CC} = 4.5\text{ V}$			20		25	ns
		$V_{CC} = 6.0\text{ V}$			15		20	ns
t_{en}	enable time	$\overline{\text{nOE}}$ to nY; see Fig. 6 [2]						
		$V_{CC} = 2.0\text{ V}$			35		40	ns
		$V_{CC} = 4.5\text{ V}$			20		25	ns
		$V_{CC} = 6.0\text{ V}$			15		20	ns
t_{dis}	disable time	$\overline{\text{nOE}}$ to nY; see Fig. 6 [3]						
		$V_{CC} = 2.0\text{ V}$			35		40	ns
		$V_{CC} = 4.5\text{ V}$			20		25	ns
		$V_{CC} = 6.0\text{ V}$			15		20	ns
t_t	transition time	see Fig. 5 [4]						
		$V_{CC} = 2.0\text{ V}$			9		11	ns
		$V_{CC} = 4.5\text{ V}$			6		8	ns
		$V_{CC} = 6.0\text{ V}$			4		5	ns
C_{PD}	power dissipation capacitance	$C_L = 15\text{ pF}$; $f = 1\text{ MHz}$; $V_I = \text{GND to } V_{CC}$ [5]		18				pF

74HC125; 74HCT125

Quad buffer/line driver; 3-state

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	
74HCT125								
t_{pd}	propagation delay	nA to nY; $V_{CC} = 4.5 \text{ V}$; see Fig. 5 [1]			20		25	ns
t_{en}	enable time	\overline{nOE} to nY; $V_{CC} = 4.5 \text{ V}$; see Fig. 6 [2]			20		25	ns
t_{dis}	disable time	\overline{nOE} to nY; $V_{CC} = 4.5 \text{ V}$; see Fig. 6 [3]			20		25	ns
t_t	transition time	$V_{CC} = 4.5 \text{ V}$; see Fig. 5 [4]			6		8	ns
C_{PD}	power dissipation capacitance	$C_L = 15 \text{ pF}$; $f = 1 \text{ MHz}$; $V_I = \text{GND to } (V_{CC} - 1.5 \text{ V})$ [5]		37				pF

[1] t_{pd} is the same as t_{PHL} and t_{PLH} .

[2] t_{en} is the same as t_{PZH} and t_{PZL} .

[3] t_{dis} is the same as t_{PLZ} and t_{PHZ} .

[4] t_t is the same as t_{THL} and t_{TLH} .

[5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

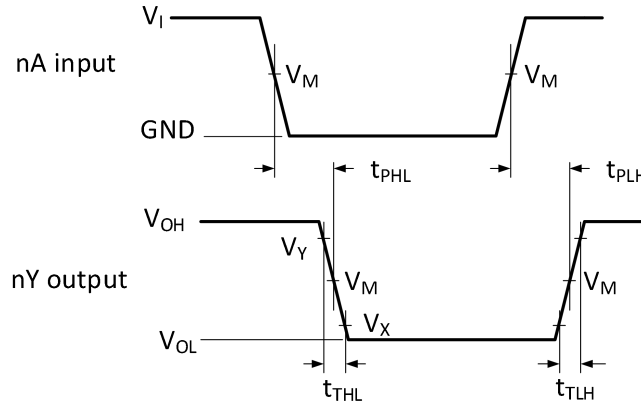
C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

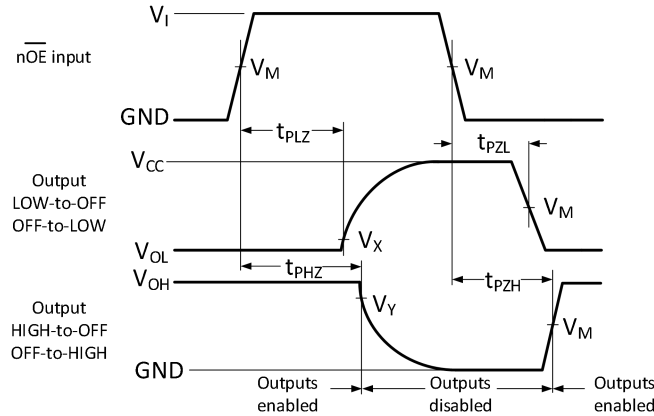
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

10.1. Waveforms and test circuit



Measurement points are given in Table 8.
 V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig. 5. The input nA to output nY propagation delays

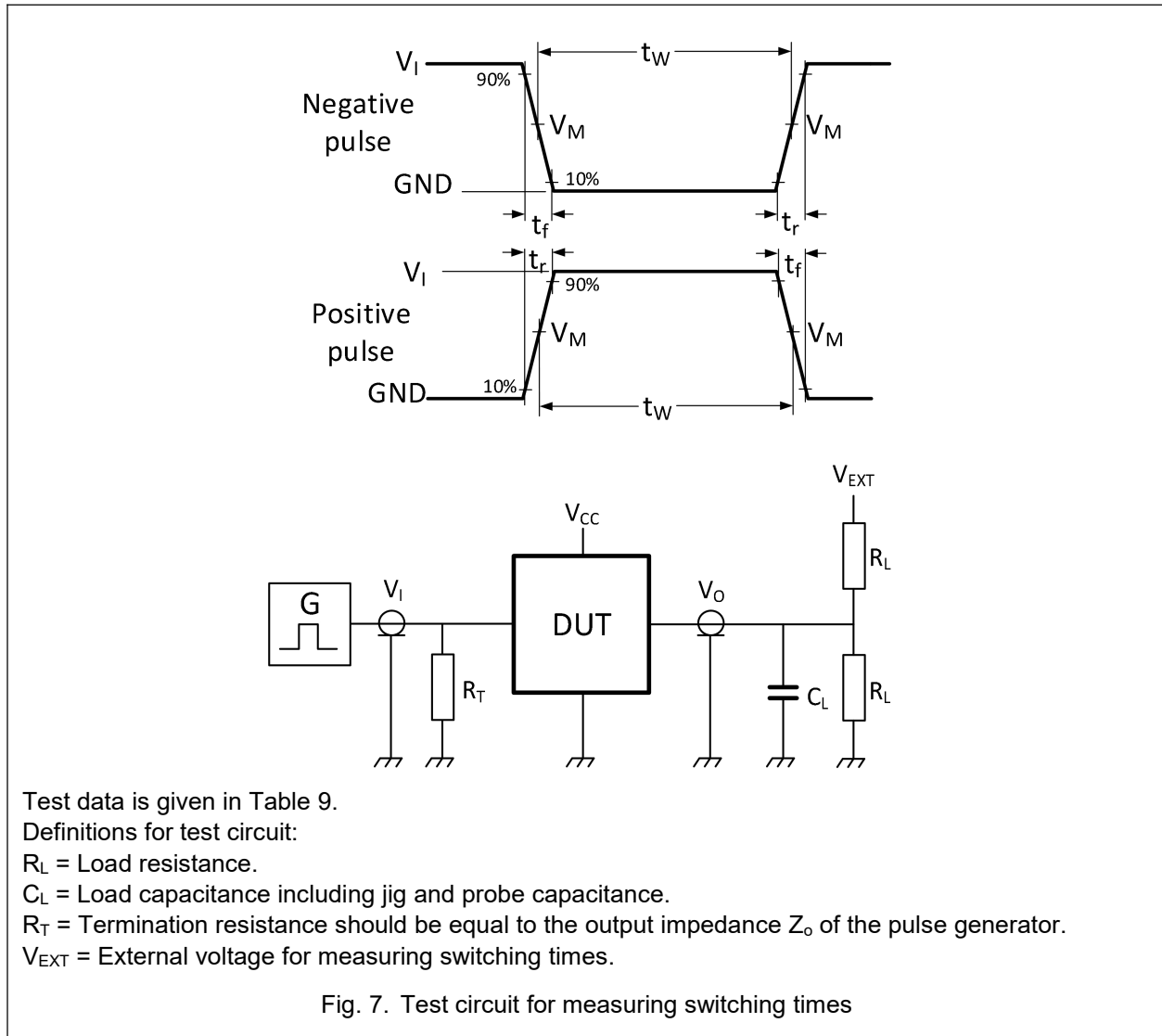


Measurement points are given in Table 8.
 V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig. 6. 3-state enable and disable times

Table 8. Measurement points

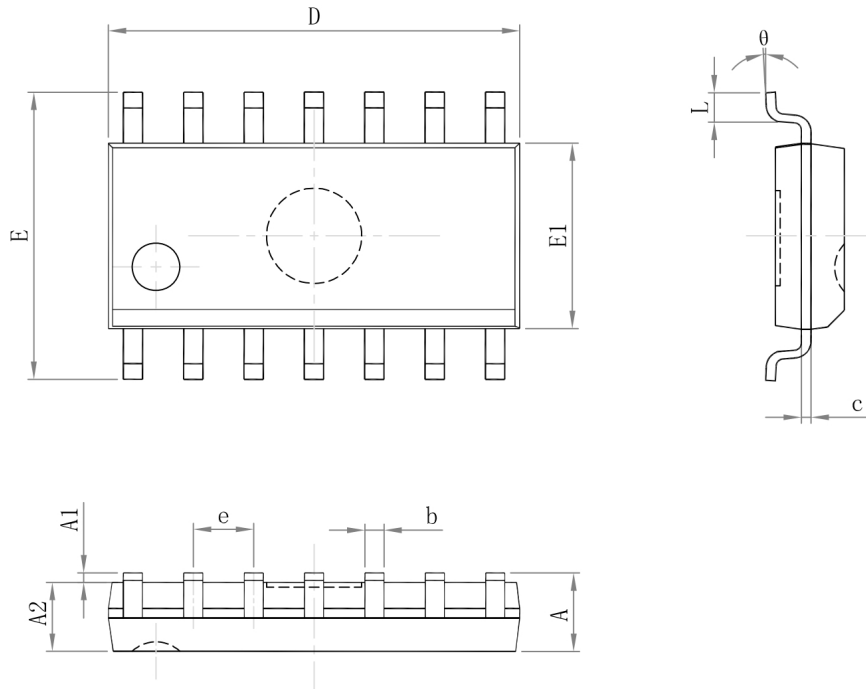
Type	Input	Output		
	V_M	V_M	V_X	V_Y
74HC125	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$
74HCT125	1.3 V	1.3 V	$0.1V_{CC}$	$0.9V_{CC}$


Table 9. Test data

Type	Input		Load		V_{EXT}		
	V_I	$t_r = t_f$	C_L	R_L	t_{PLH}, t_{PHL}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74HC125	V_{CC}	≤ 2.5 ns	15 pF	500 Ω	open	GND	$2V_{CC}$
74HCT125	3 V	≤ 2.5 ns	15 pF	500 Ω	open	GND	$2V_{CC}$

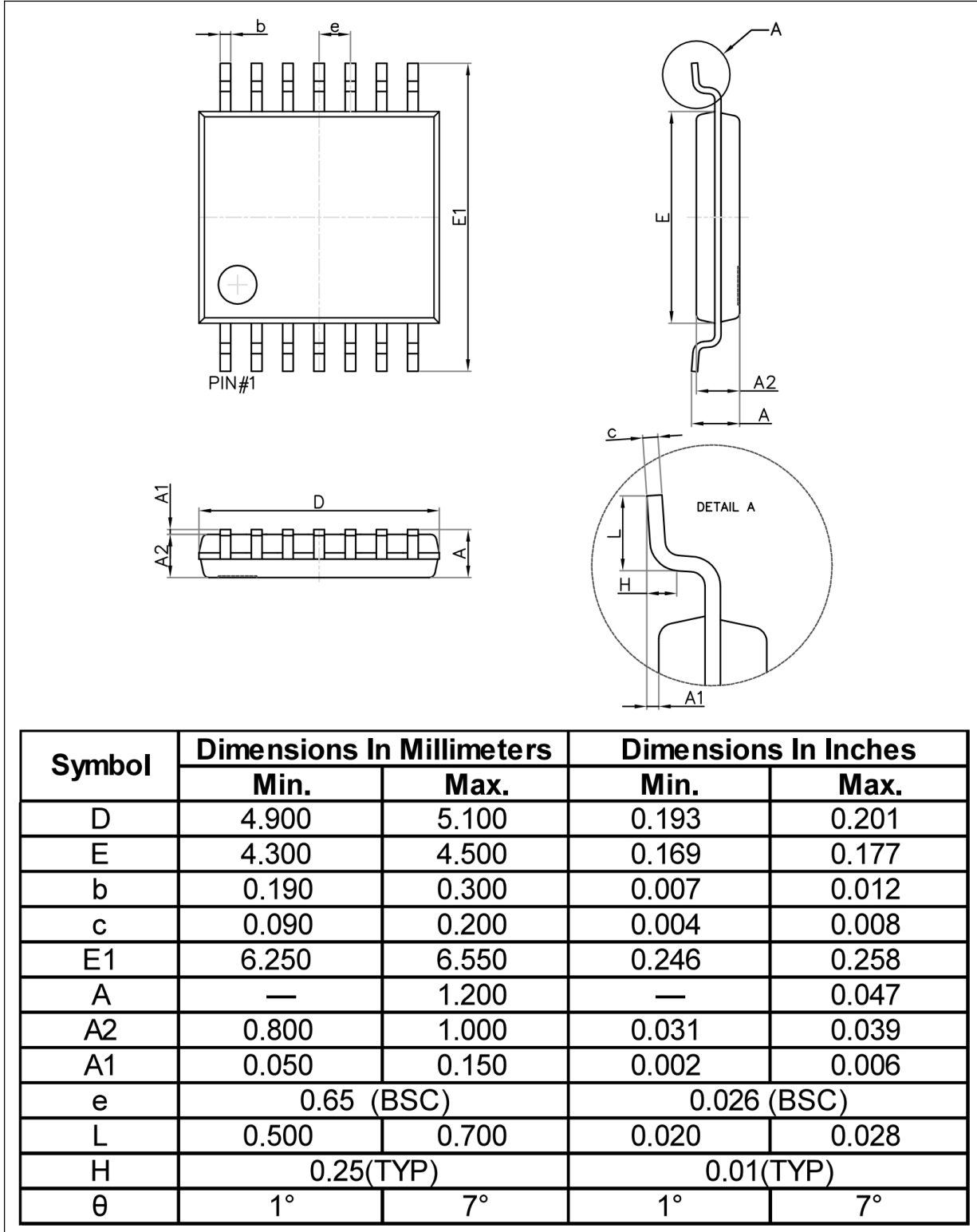
11. Package Outline

SOP-14L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	--	1.750	--	0.069
A1	0.100	0.250	0.004	0.010
A2	1.250	--	0.049	--
b	0.310	0.510	0.012	0.020
c	0.100	0.250	0.004	0.010
D	8.450	8.850	0.333	0.348
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
theta	0°	8°	0°	8°

TSSOP-14L



12. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
CDM	Charged Device Model
TTL	Transistor-Transistor Logic

13. Revision History

Table 11. Revision history

Document ID	Release Date	Data sheet status	Change notice	Supersedes
74HC_HCT125 Rev. 1.0	Aug 08, 2024	Product datasheet		